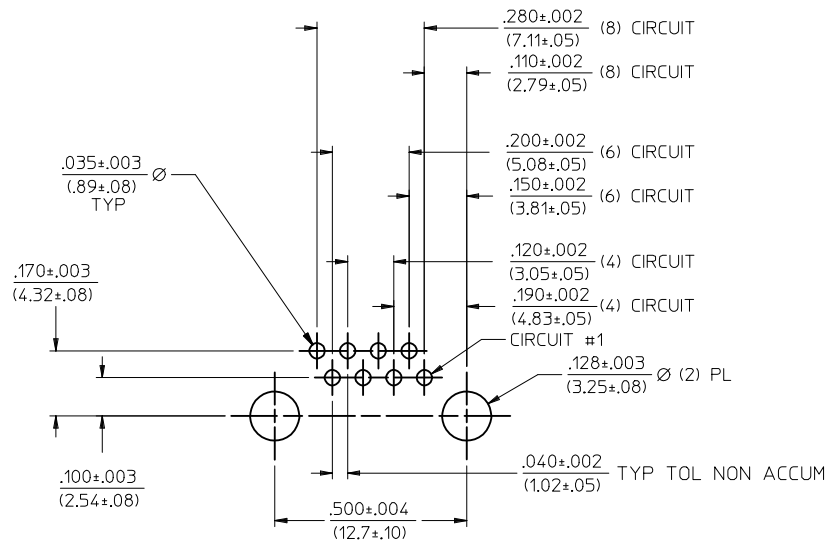
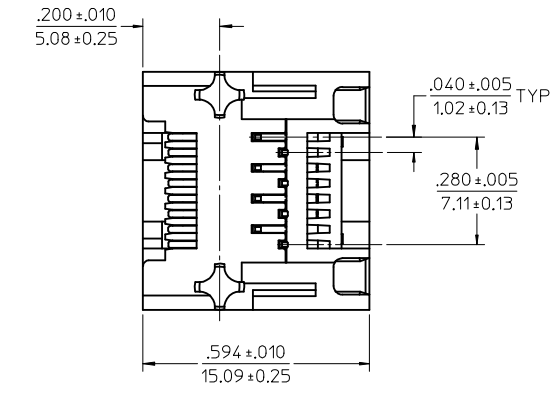
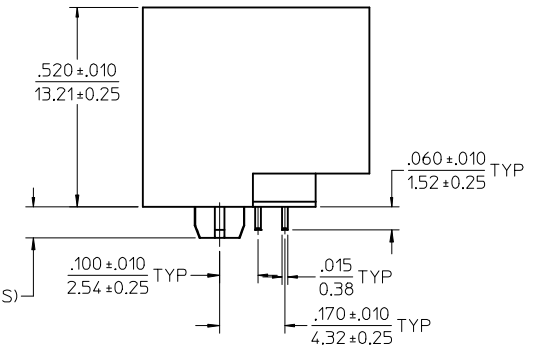
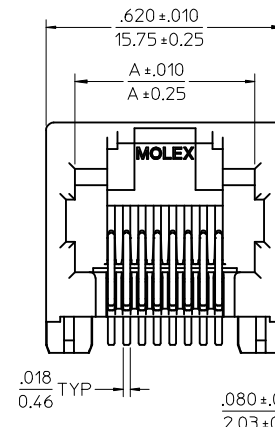


NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN EXTRUDED TUBES
PER PACKAGING SPECIFICATION PK-43860-004
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR
REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



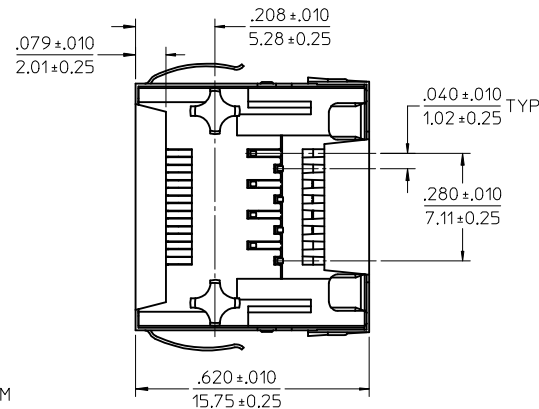
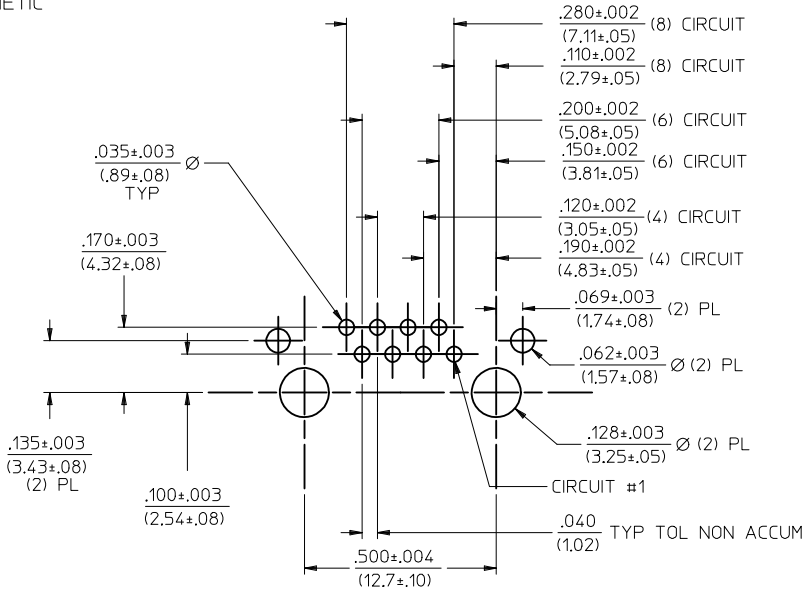
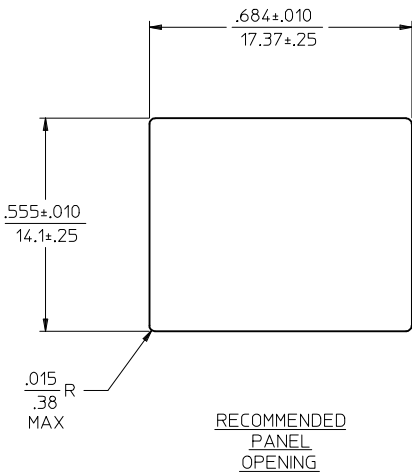
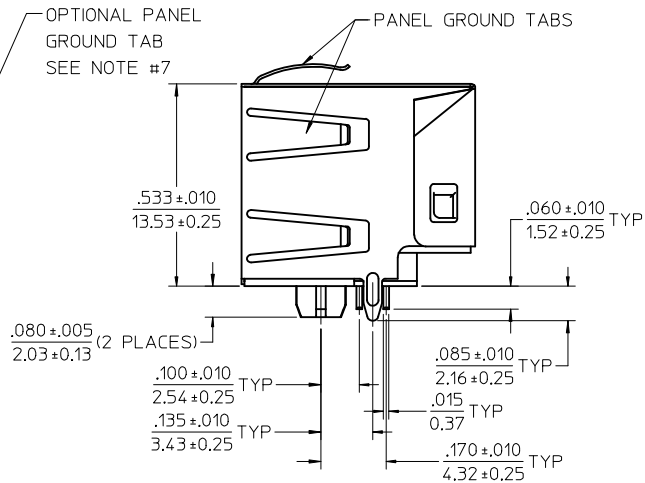
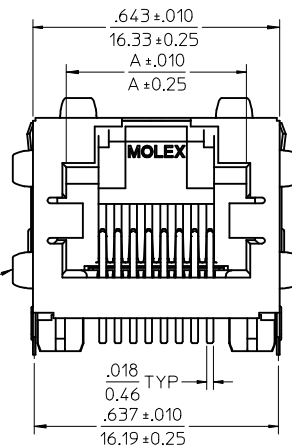
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS .039/1.00

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0001	8	.470/11.94	8
44380-0002	6	.389/9.88	6

ADD PN 44380-0004 EC NO: UCP2017-0909 DRAWN: AFENG02 2016/10/24 CHKD: APPR: KLANG 2016/10/28 REV: C4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	DRAWN BY MAYO DATE 1999/04/09	TITLE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex SD-44380-001	SHEET NO. 1 OF 5
	▽=0	3 PLACES ± --- ± ---	CHECKED BY ROBERTS DATE 1999/04/09	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		
	▽=0	2 PLACES ± --- ± ---	APPROVED BY ROBERTS DATE 1999/04/09	ANGULAR ±1/2°		
▽=0	1 PLACE ± --- ± ---	MATERIAL NO.	DOCUMENT NO.			
		0 PLACE ± --- ± ---	SEE CHART			

NOTES

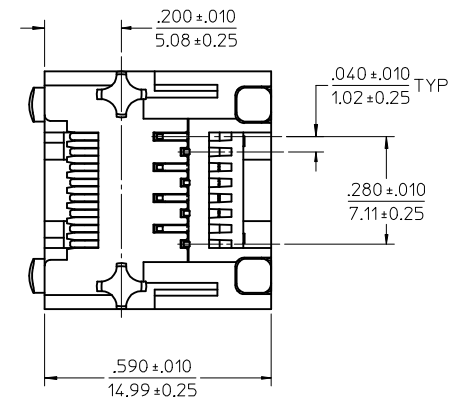
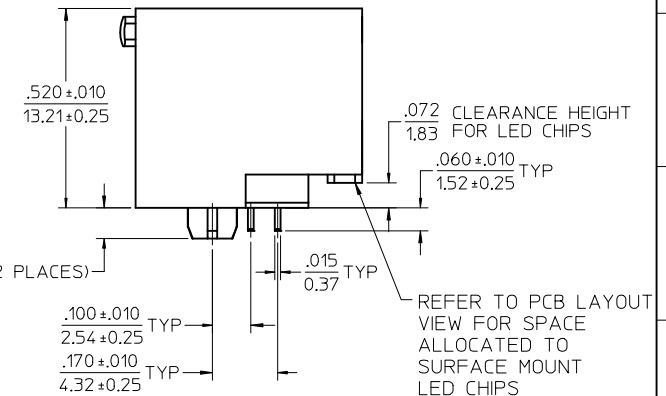
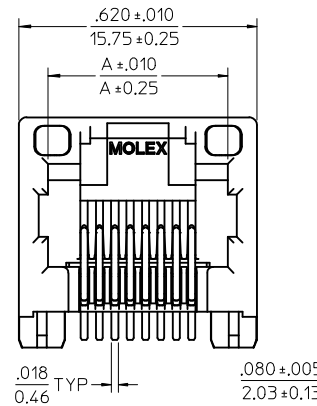
- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005
OPTION (44380-2004 AND 44380-2013) PACKAGED IN TAPE AND REEL
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0004	8	.470/11.94	8	ALL
44380-0013	8	.470/11.94	8	SEE NOTE #7
44380-2004	8	.470/11.94	8	ALL
44380-2013	8	.470/11.94	8	SEE NOTE #7

SEE SHEET 1 EC NO: UCP2017-0909 DRWNAFENG02 2016/10/24 CHKD: APPR:KLANG 2016/10/28 REV: C4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	IN/MM	4:1	INCH	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± ---	MAYO 1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)		
	2 PLACES ± --- ± ---	CHECKED BY DATE				
	1 PLACE ± --- ± ---	ROBERTS 1999/04/09				
	0 PLACE ± --- ± ---	APPROVED BY DATE				
		ROBERTS 1999/04/09				
		ANGULAR ±1/2°	MATERIAL NO.	DOCUMENT NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE CHART	SD-44380-001		SHEET NO. 2 OF 5
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

- NOTES
- MATERIAL:
HOUSING:
GLASS FILLED NYLON, 94V-0, COLOR: BLACK
TERMINALS:
PHOSPHOR BRONZE, .015/(0.38) THK
LIGHTPIPE:
POLYCARBONATE- WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - PLATING:
TERMINAL:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - PACKAGING SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
 - PACKAGING:
PER PACKAGING SPECIFICATION PK-43860-004
 - APPLICATION SPECIFICATION: AS-43860-001.
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
 - REFER TO PAGE (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

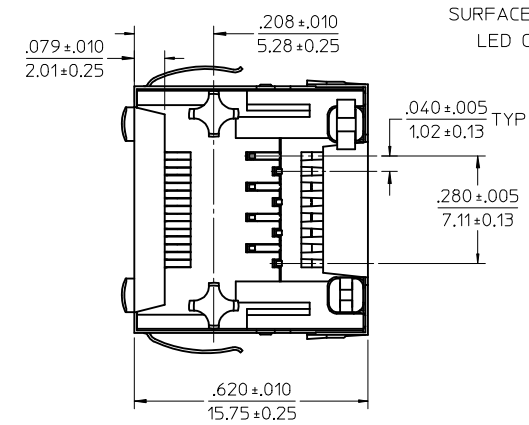
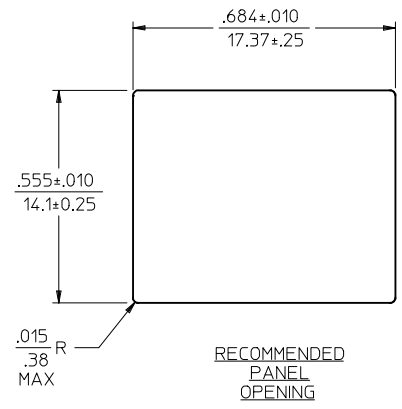
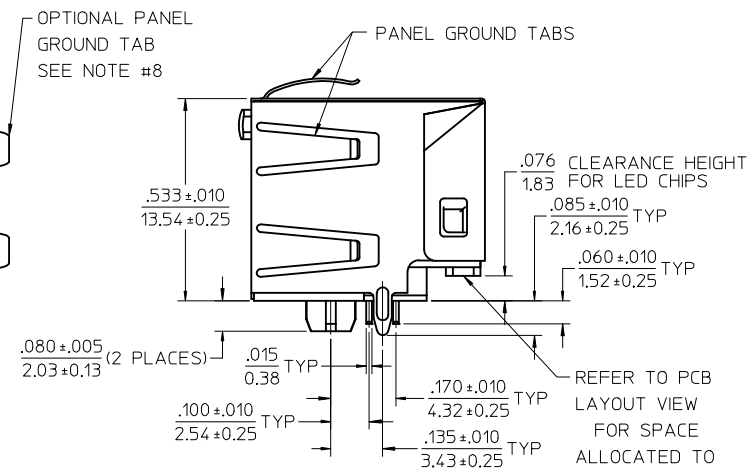
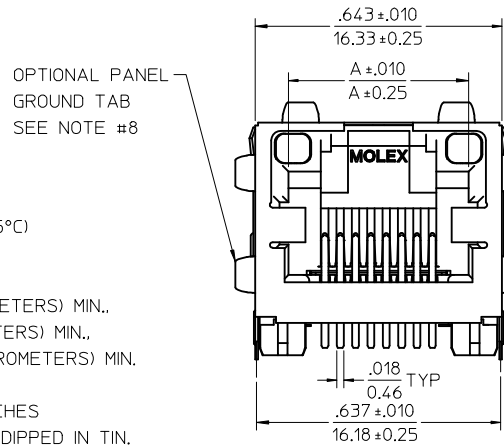


MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0007	POLYCARBONATE	8	.470/11.94	8

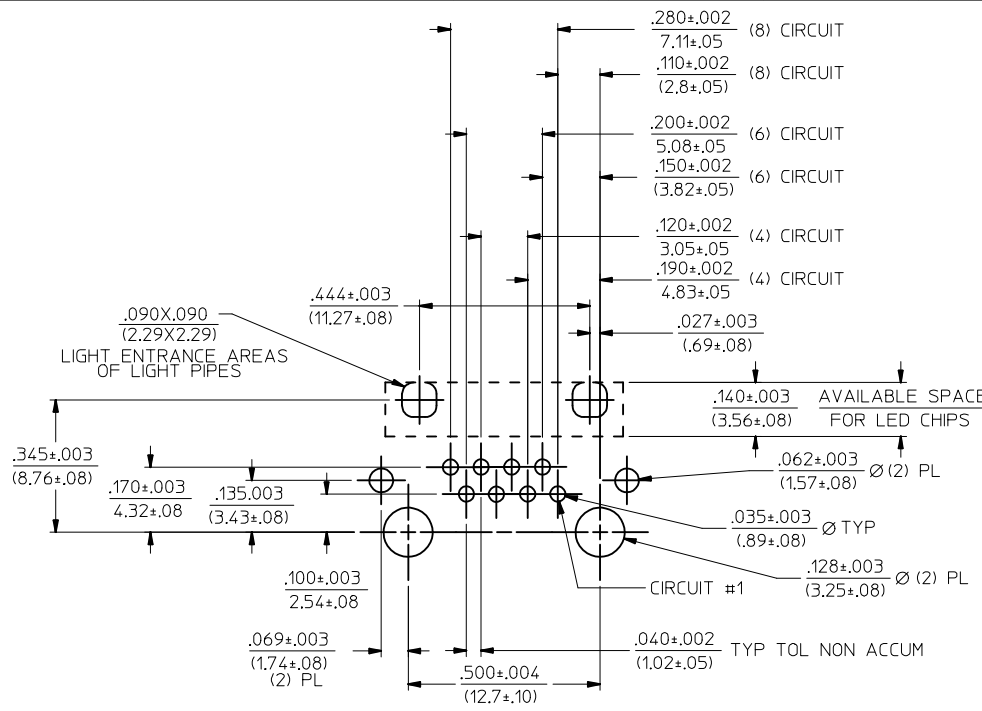
SEE SHEET 1 EC NO: UCP2017-0909 DRAWN: AFENG02 2016/10/24 CHKD: APPR: KLANG 2016/10/28 REV: C4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	IN/MM	4:1	INCH	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex	
	▽=0	3 PLACES ± --- ± ---	MAYO 1999/04/09	SEE CHART		
	2 PLACES ± --- ± ---	CHECKED BY DATE	ROBERTS 1999/04/09	SD-44380-001	SHEET NO.	
	1 PLACE ± --- ± ---	APPROVED BY DATE	ROBERTS 1999/04/09		3 OF 5	
	0 PLACE ± --- ± ---	MATERIAL NO.	SEE CHART	DOCUMENT NO.		
	ANGULAR ±1/2°	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

NOTES

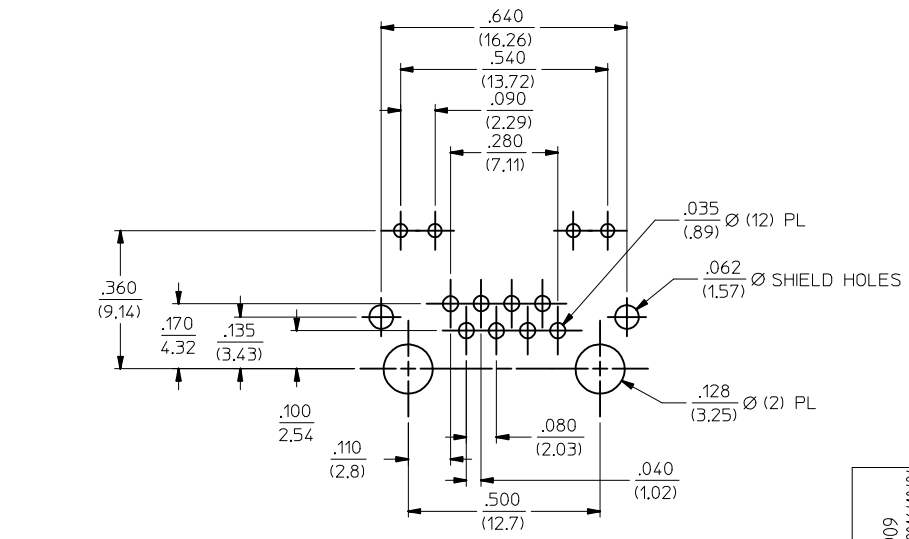
- 1) MATERIAL:
 - HOUSING: GLASS FILLED NYLON, 94V-0, COLOR: BLACK
 - TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THK
 - SHIELD: BRASS
 - LIGHTPIPE: POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
 - POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) PLATING:
 - TERMINAL: SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN., SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - SHIELD: 100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN.
- 3) PRODUCT SPECIFICATION: CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX PRODUCT SPECIFICATION PS-43860-003.
- 4) PACKAGING: CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER PACKAGING SPECIFICATION PK-44380-005 .
- 5) APPLICATION SPECIFICATION: AS-43860-001.
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



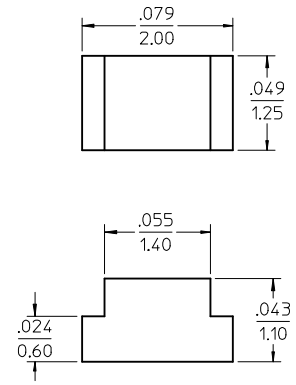
A	MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONN SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS	SEE SHEET 1 EC NO: UCP2017-0909 DRWNAFENG02 2016/10/24 CHKD: APPR:KLANG 2016/10/28 DESCRIPTION	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- 0 PLACE ± ± ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-44380-001	SHEET NO. 4 OF 5
	44380-0016	POLYCARBONATE	8	.470/11,94	8	SEE NOTE #8											



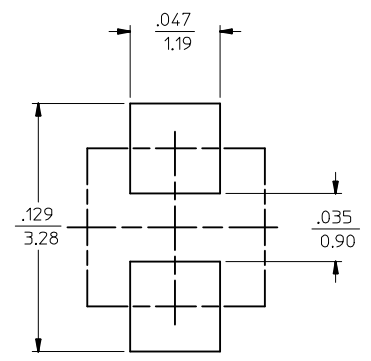
MOLEX RECOMMENDED
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00



TYPICAL COMPETITION
PCB LAYOUT WITH
INTEGRAL LED'S
(SHOWN FOR REFERENCE ONLY)
RECOMMENDED PC BOARD THICKNESS: .039/1.00



RECOMMENDED SMT
LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1 EC NO: UCP2017-0909 DRAWN: FENGZ 2016/10/24 CHKD: APPR: KLANG 2016/10/28	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
				DRAWN BY MAYO	DATE 1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)			
				CHECKED BY ROBERTS	DATE 1999/04/09				
				ANGULAR ±1/2°		MATERIAL NO.	DOCUMENT NO. SD-44380-001		SHEET NO. 5 OF 5
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					